



TEST TECHNOLOGY TC NEWSLETTER

PAST TTTC EVENTS

International Test Conference (ITC) and TestWeek 2008

26-31 October 2008
Santa Clara, California
<http://www.itctestweek.org>

The International Test Conference, the cornerstone of TestWeek, is the world's premier conference dedicated to the electronic test of devices, boards, and systems, covering the complete cycle from design verification, test, diagnosis, failure analysis, and back to process and design improvement. TestWeek includes two days of tutorials, a three-day conference program, and two days of workshops. There is also a large exhibit floor with the latest equipment, software, services, and tools for solving test problems.

ITC 2008 was held in Santa Clara, California. There were 17 tutorials, covering a wide range of topics. Mike Lydon (vice president of Technology and Quality, Global Supply Chain Management at Cisco Systems) gave the keynote address. He discussed the role of test in managing very large end-to-end supply chains. There were also three invited talks, one on each of the three days of the conference: Jan Rabaey (professor at the University of California, Berkeley) spoke about technologies of the future and their challenges for test. Bob Pease (staff scientist at National Semiconductor) shared some of his experiences from 48 years in analog design and test. Jeff Rearick (Fellow at Advanced Micro Devices) explained how to determine whether DFT and test are adding value to your company. There were 35 technical-paper sessions, four advanced-industrial-practice sessions, four lecture series, and six panels. New features for ITC 2008 included two embedded tutorials in the regular technical program, two hot-topic background sessions, and a poster session.

This report was written by 2008 ITC Program Chair Nur Touba (University of Texas at Austin). Contact him at touba@ece.utexas.edu.

UPCOMING TTTC EVENTS

10th IEEE Latin-American Test Workshop (LATW 09)

2-5 March 2009
Búzios, Brazil
<http://inf.ufrgs.br/latw>

LATW provides an annual forum for test and fault tolerance professionals and technologists from Latin America and throughout the world to discuss various aspects of system, board, and component testing and fault tolerance with design, manufacturing, and field considerations in mind.

Design, Automation and Test in Europe Conference (DATE 09)

20-24 April 2009
Nice, France
<http://www.date-conference.com>

DATE is the premier European event in hardware and software design, test, and manufacturing of electronic circuits and systems, for designers; design automation users, researchers, and vendors; and specialists. It particularly emphasizes ICs and SoCs, reconfigurable hardware, and embedded systems, including embedded software. The five-day event consists of a conference with plenary invited papers, regular papers, panels, hot-topic sessions, tutorials, and workshops, plus two special focus days and a track for executives. The scientific conference is complemented by a commercial exhibition of the state of the art in design and test tools, methodologies, IP and design services, reconfigurable and other hardware platforms, embedded software, and industrial design experiences from different application domains (such as automotive, wireless, telecommunications, and multimedia applications). DATE 2009 has received a record numbers of submissions (over 960) with a 30% increase in papers on industrial applications.

27th IEEE VLSI Test Symposium (VTS 09)

3-7 May 2009

Santa Cruz, California

http://www.tttc-vts.org/public_html/new/2009/index.php

The IEEE VLSI Test Symposium explores emerging trends and novel concepts in test, verification, and validation of microelectronic circuits and systems, analog and RF circuits, digital circuits, FPGAs, embedded systems, and memory. In addition to the high-quality papers presented at VTS, the innovative-practices track and special sessions are popular among researchers from both academia and industry. The innovative-practices track highlights cutting-edge challenges faced by test practitioners and the innovative solutions employed to address them. Special sessions can include panels, embedded tutorials, or hot-topic presentations.

IEEE European Test Symposium (ETS 09)

25-29 May 2009

Seville, Spain

<http://www.imse.cnm.es/ets09>

ETS is Europe's premier forum dedicated to presenting and discussing scientific results, emerging ideas, practical applications, hot topics, and new trends in the area of electronic-based circuits and systems testing.

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CALL FOR PAPERS

International Test Conference (ITC) and TestWeek 2009

2-6 November 2009

Austin, Texas

<http://www.itctestweek.org>

International Test Conference, the cornerstone of TestWeek, is the world's premier conference on electronic test of devices, boards, and systems. ITC covers the complete cycle from design verification to test, diagnosis, failure analysis, and back to process and design improvement. Test and design professionals can confront the challenges the industry faces, and learn how these challenges are being addressed by the combined efforts of academia, design tool and equipment suppliers, designers, and test engineers.

Submissions deadline: 7 March 2009

NEWSLETTER EDITOR'S INVITATION

I would appreciate input and suggestions about the newsletter from the test community. Please forward your ideas; contributions; and information on awards, conferences, and workshops to Mohammad Tehranipoor, Electrical and Computer Engineering Department, Univ. of Connecticut, 371 Fairfield Way, Storrs, CT 06269-2157; tehrani@engr.uconn.edu.

Mohammad Tehranipoor
Editor, TTTC Newsletter

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